

IN THE CLAIMS

Claims 1-39: Canceled.

40. (Currently Amended) An electronic component, comprising:
- a candidate substrate; and
- a candidate polymer, wherein the candidate polymer comprises a high adhesive strain component with respect to the candidate substrate; and
- wherein the candidate substrate and the candidate polymer are coupled to one another to form an interface formed from the substrate and the polymer couple, and wherein the substrate and the polymer are selected as candidates based on a ~~computer assisted model software program~~.
41. (Currently Amended) The electronic component of claim 40, wherein the ~~computer assisted model software program~~ comprises strain cycling data.
42. (Currently Amended) The electronic component of claim 40, wherein the ~~computer assisted model software program~~ evaluates at least one property of the interface, including size, shape and bond geometry.
43. Canceled.
44. (Currently Amended) The electronic component of claim 40, wherein the candidate polymer comprises at least one of the following chemical precursors: tris(2,3-epoxypropyl)isocyanurate; 1,3,5-tris(2-hydroxyethyl) 1,3,5-triazine 2,4,6-(1H, 3H, 5H) trione; bis(2,3-epoxycyclopentyl ether); 4,4'-oxydianiline; bisphenol A glycidyl ether and bis(3,4-epoxycyclohexylmethyl)adipate.
45. (Currently Amended) The electronic component of claim 40, wherein the candidate polymer is amorphous, crosslinked, crystalline or branched.

46. (Currently Amended) The electronic component of claim 45, wherein the candidate polymer is crosslinked.
47. Canceled.
48. (Currently Amended) The electronic component of claim 47 42, wherein ~~each of the plurality of candidate interfaces comprises software program evaluates at least one of the~~ following: a set of modeling data, a set of durability data or a set of evaluation data.
49. (Currently Amended) An electronic component, comprising:
 - a candidate substrate;
 - a candidate first polymer; and
 - a candidate second polymer, wherein the candidate first polymer comprises a high adhesive strain component with respect to the candidate substrate and the candidate second polymer and wherein the candidate second polymer comprises a high adhesive strain component with respect to the candidate first polymer; and
wherein the candidate substrate, the candidate first polymer and the candidate second polymer are coupled to one another to form an interface formed from the substrate and the polymer couple, and wherein first polymer and the second polymer are selected as candidates based on a ~~computer-assisted model~~ software program.
50. (Currently Amended) The electronic component of claim 49, wherein the ~~computer-assisted model~~ software program comprises strain cycling data.
51. (Currently Amended) The electronic component of claim 49, wherein the ~~computer-assisted model~~ software program evaluates at least one property of the interface, including size, shape and bond geometry.
52. Canceled.
53. (Currently Amended) The electronic component of claim 49, wherein at least one of the

candidate first polymer or the second candidate polymer comprises at least one of the following chemical precursors: tris(2,3-epoxypropyl)isocyanurate; 1,3,5-tris(2-hydroxyethyl) 1,3,5-triazine 2,4,6-(1H, 3H, 5H) trione; bis(2,3-epoxycyclopentyl ether); 4,4'-oxydianiline; bisphenol A glycidyl ether and bis(3,4-epoxycyclohexylmethyl)adipate.

54. (Currently Amended) The electronic component of claim 49, wherein at least one of the first candidate polymer or the second candidate polymer is amorphous, crosslinked, crystalline or branched.
55. (Currently Amended) The electronic component of claim 53, wherein at least one of the first candidate polymer or the second candidate polymer is crosslinked.
56. (New) The electronic component of one of claims 41 or 50, wherein the high adhesive strain component is determined by the software program.
57. (New) The electronic component of one of claims 41 or 50, wherein the software program determines strain intercept.